

Title (en)  
HEAT PUMP DEVICE

Title (de)  
WÄRMEPUMPENVORRICHTUNG

Title (fr)  
DISPOSITIF DE POMPE À CHALEUR

Publication  
**EP 3531041 B1 20220706 (EN)**

Application  
**EP 16919027 A 20161019**

Priority  
JP 2016081009 W 20161019

Abstract (en)  
[origin: EP3531041A1] A heat pump device includes: a housing accommodating a compressor configured to compress a refrigerant, a first heat exchanger configured to exchange heat between the refrigerant and air, a blower, and a second heat exchanger configured to exchange heat between the refrigerant and a heat medium; a partition plate configured to partition a space in the housing into a machine compartment in which the compressor is accommodated, and a blower compartment in which the first heat exchanger, the blower, and the second heat exchanger are accommodated; and an internal heat exchanger accommodated in the machine compartment, the internal heat exchanger exchanging heat between the refrigerant having passed through the first heat exchanger and the refrigerant having passed through the second heat exchanger. The internal heat exchanger is supported by the partition plate.

IPC 8 full level  
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